

Supporting Information

Transport Limitations and Defect-Mediated Recombination in Lead-Free Double Perovskite $\text{Cs}_2\text{AgSbI}_6$: Implications for Solar-Cell Design

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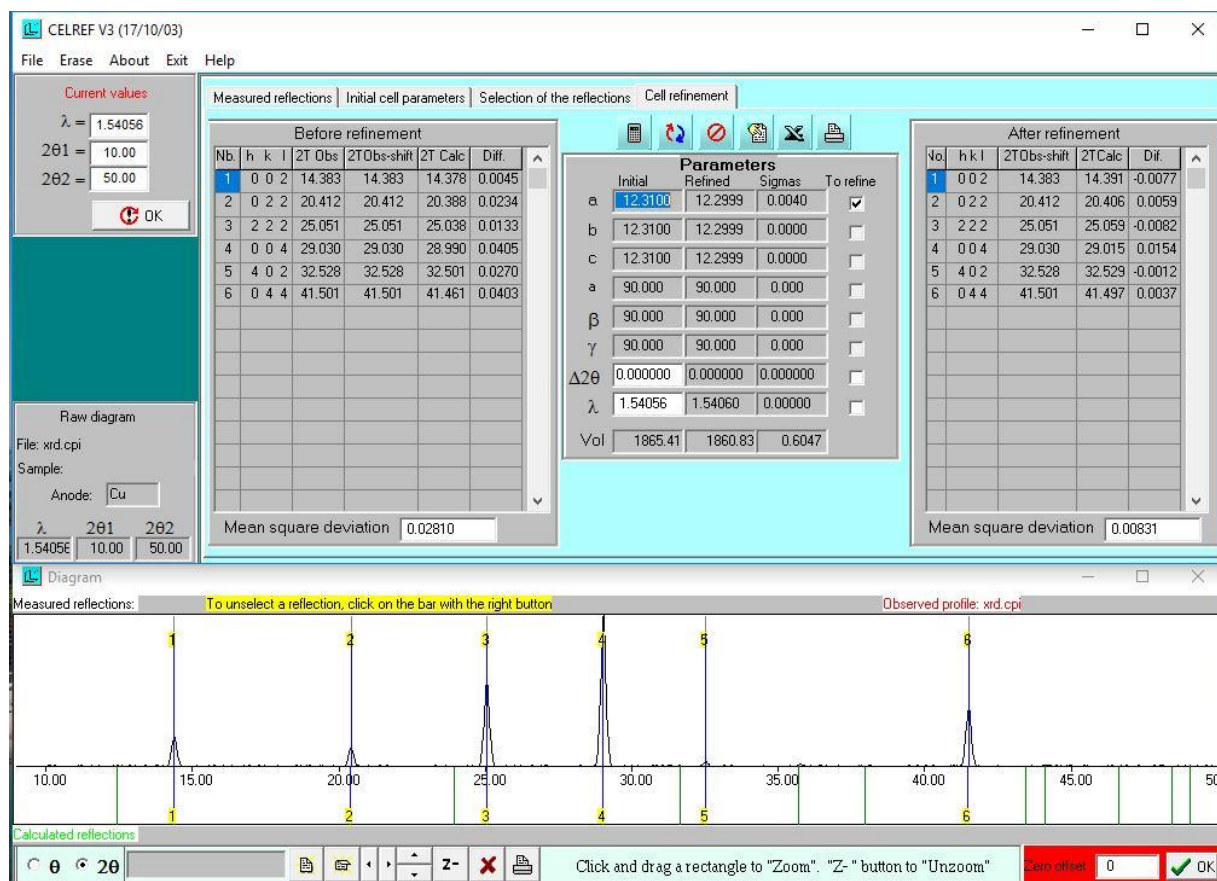
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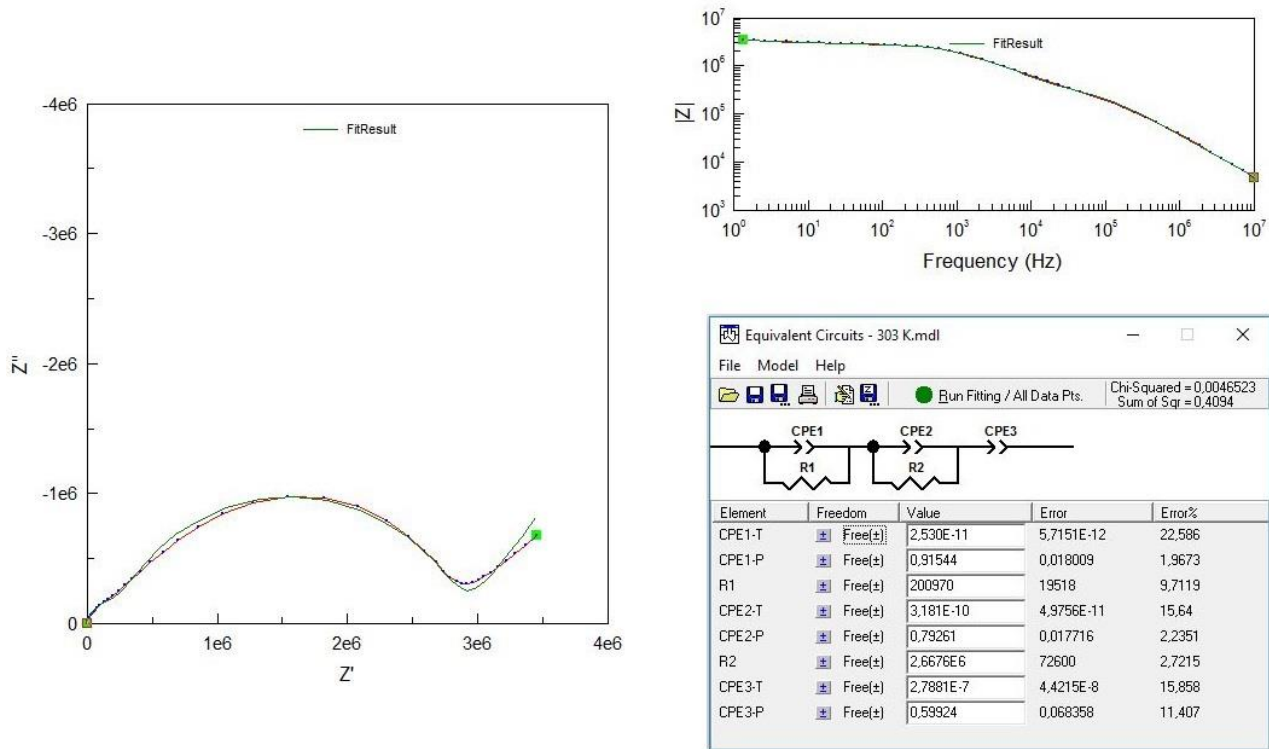
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S1. Supplementary Figures



Figs. S1. CELREF refinement of the room-temperature X-ray diffraction pattern of polycrystalline $\text{Cs}_2\text{AgSbI}_6$ assuming a cubic double-perovskite structure.



Figs. S2. Representative impedance spectrum of polycrystalline $\text{Cs}_2\text{AgSbI}_6$ measured at 303 K under dark conditions together with the corresponding equivalent-circuit fitting.

S2. SCAPS-1D simulation methodology and input parameters

numerical simulations were performed using SCAPS-1D version 3.3.09 (ELIS–UGent). The simulated device architecture corresponds to:

FTO / TiO_2 / $\text{Cs}_2\text{AgSbI}_6$ / Spiro-OMeTAD / metal contact

All simulations were carried out at 300 K under AM1.5G illumination (1000 W m^{-2}) unless otherwise stated. The simulations were designed to translate experimentally observed bulk recombination and transport limitations into a device-level framework, rather than to model an optimized photovoltaic device.

S3. Bulk material parameters

Table S1. SCAPS-1D input parameters for Spiro-OMeTAD (HTL)

Parameter	Symbol	Value	Unit
Thickness	d	200	nm
Band gap	E_g	3.0	eV
Electron affinity	χ	2.4	eV
Dielectric constant	ϵ_r	3.0	—
Electron mobility	μ_n	2×10^{-4}	$\text{cm}^2 \text{V}^{-1} \text{s}^{-1}$
Hole mobility	μ_p	2×10^{-4}	$\text{cm}^2 \text{V}^{-1} \text{s}^{-1}$
Acceptor density	N_A	1×10^{18}	cm^{-3}
Donor density	N_D	0	cm^{-3}

Table S2. SCAPS-1D input parameters for $\text{Cs}_2\text{AgSbI}_6$ absorber

Parameter	Symbol	Value	Unit
Thickness	d	600	nm
Band gap	E_g	1.65	eV
Electron affinity	χ	4.0	eV
Dielectric constant	ϵ_r	10.0	—
Electron mobility	μ_n	1.0	$\text{cm}^2 \text{V}^{-1} \text{s}^{-1}$
Hole mobility	μ_p	0.5	$\text{cm}^2 \text{V}^{-1} \text{s}^{-1}$
Acceptor density	N_A	1×10^{15}	cm^{-3}
Donor density	N_D	0	cm^{-3}

Bulk defect density	N_t	$5 \times 10^{18} - 1 \times 10^{20}$	cm^{-3}
Defect type	–	Neutral	–
Defect energy level	E_t	$E_c - 0.10$	eV
Electron lifetime	τ_n	0.01	ns
Hole lifetime	τ_p	0.01	ns

Table S3. SCAPS-1D input parameters for TiO₂ (ETL)

Parameter	Symbol	Value	Unit
Thickness	d	50	nm
Band gap	E_g	3.2	eV
Electron affinity	χ	4.0	eV
Dielectric constant	ϵ_r	9.0	–
Electron mobility	μ_n	10	$\text{cm}^2 \text{V}^{-1} \text{s}^{-1}$
Hole mobility	μ_p	1×10^{-4}	$\text{cm}^2 \text{V}^{-1} \text{s}^{-1}$
Donor density	N_D	1×10^{18}	cm^{-3}

Table S4. SCAPS-1D input parameters for FTO (TCO)

Parameter	Symbol	Value	Unit
Thickness	d	500	nm
Band gap	E_g	3.5	eV
Electron affinity	χ	4.0	eV
Dielectric constant	ϵ_r	9.0	–

Electron mobility	μ_n	20	$\text{cm}^2 \text{V}^{-1} \text{s}^{-1}$
Donor density	N_D	1×10^{20}	cm^{-3}

S3. Interface defect parameters

Table S5. Interface defect states

Interface	N_t	Unit	E_t	$S_n = S_p$
Spiro-OMeTAD / $\text{Cs}_2\text{AgSbI}_6$	1×10^{14}	cm^{-2}	E_i	$1 \times 10^4 \text{ cm s}^{-1}$
$\text{Cs}_2\text{AgSbI}_6$ / TiO_2	1×10^{12}	cm^{-2}	E_i	$1 \times 10^2 \text{ cm s}^{-1}$

All interface states were assumed neutral with single-level energy distributions.

S4. Contact parameters

Table S6. Electrical contact properties

Contact	Work function (eV)	Electron SRV (cm s^{-1})	Hole SRV (cm s^{-1})
Back contact (metal / Spiro-OMeTAD)	5.1	1×10^5	1×10^7
Front contact (FTO / TiO_2)	4.4	1×10^7	1×10^5

Ohmic contacts were intentionally assumed to isolate bulk and interfacial recombination effects from contact-limited transport.

S5. Numerical and measurement conditions (Action Panel settings)

The current–voltage characteristics were calculated using the following numerical settings:

- Temperature: 300 K
- Illumination spectrum: AM1.5G (1000 W m^{-2})
- Voltage scan range: -0.20 V to $+1.20 \text{ V}$
- Voltage step: 0.01 V

- Number of points: 141
- Series resistance: $R_s = 10 \Omega \cdot \text{cm}^2$
- Shunt resistance: $R_{sh} = 1 \times 10^{30} \Omega \cdot \text{cm}^2$
- Radiative and Auger recombination: neglected
- Recombination mechanism: Shockley–Read–Hall (SRH)

Dark and illuminated conditions were simulated using identical numerical settings, except for the illumination source.

S6. Reproducibility statement

All figures reported in the main manuscript were generated using the parameters summarized above. The Supplementary Information provides full numerical transparency to ensure reproducibility and facilitate comparison with future experimental and simulation studies.